# DC-DC Converter (-20V, -2.0A)

# RTL020P02

#### Features

- 1) Low on-resistance. ( $80m\Omega$  at 2.5V)
- 2) High power package.
- 3) High speed switching.
- 4) Low voltage drive. (2.5V)

# Applications

DC-DC converter

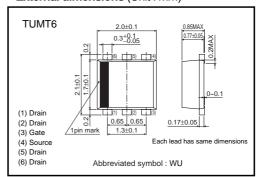
# ●Structure

Silicon P-channel MOS FET

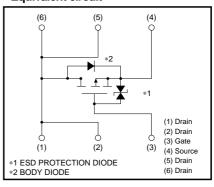
## Packaging specifications

	Package	Taping	
Type	Code	TR	
	Basic ordering unit (pieces)	3000	
RTL020P02	0		

### ●External dimensions (Unit : mm)



#### ●Equivalent circuit



# ●Absolute maximum ratings (Ta=25°C)

Parameter		Symbol	Limits	Unit	
Drain-source voltage		VDSS	-20	V	
Gate-source voltage		Vgss	±12	V	
Drain augrant	Continuous	lσ	±2	Α	
Drain current	Pulsed	IDP	±8	Α *	
Source current	Continuous	Is	-0.8	Α	
(Body diode)	Pulsed	Isp	-3.2	Α	
Total power dissipation		Po	1	W *	
Channel temperature		Tch	150	°C	
Range of Storage temperature		Tstg	-55 to +150	°C	
(Body diode) Pulsed  Total power dissipation  Channel temperature		Isp PD Tch	-3.2 1 150	A W °C	

# ●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions	
Gate-source leakage	I <sub>GSS</sub>	-	-	±10	μΑ	V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V	
Drain-source breakdown voltage	V <sub>(BR)</sub> DSS	-20	-	_	V	I <sub>D</sub> = -1mA, V <sub>GS</sub> =0V	
Zero gate voltage drain current	IDSS	_	_	-1	μΑ	Vps= -20V, Vgs=0V	
Gate threshold voltage	VGS (th)	-0.7	_	-2.0	V	V <sub>DS</sub> = -10V, I <sub>D</sub> = -1mA	
Static drain-source on-state resistance	R <sub>DS (on)</sub>	_	100	135	mΩ	I <sub>D</sub> = -2A, V <sub>G</sub> S= -4.5V	
		-	110	150	mΩ	I <sub>D</sub> = -2A, V <sub>GS</sub> = -4V	
		_	180	250	mΩ	I <sub>D</sub> = -1A, V <sub>G</sub> S= -2.5V	
Forward transfer admittance	Y <sub>fs</sub> *	1.2	-	_	S	V <sub>DS</sub> = -10V, I <sub>D</sub> = -1A	
Input capacitance	Ciss	-	430	_	pF	V <sub>DS</sub> = -10V	
Output capacitance	Coss	-	80	_	pF	V <sub>GS</sub> =0V	
Reverse transfer capacitance	Crss	-	55	_	pF	f=1MHz	
Turn-on delay time	td (on) *	_	11	_	ns	ID= -1A	
Rise time	tr *	_	13	_	ns	VDD≒ -15V	
Turn-off delay time	t <sub>d (off)</sub> *	-	38	_	ns	V <sub>GS</sub> = -4.5V R <sub>L</sub> =15Ω	
Fall time	t <sub>f</sub> *	_	12	_	ns	RGS= $10\Omega$	
Total gate charge	Qg	_	4.9	_	nC	V <sub>DD</sub> ≒−15V RL≒7.5Ω	
Gate-source charge	Qgs	_	1.2	_	nC	V <sub>GS</sub> = -4.5V R <sub>GS</sub> =10Ω	
Gate-drain charge	Q <sub>gd</sub>	_	1.3	_	nC	I <sub>D</sub> = -2A	

Body diode characteristics (source-drain characteristics)

Forward voltage	VSD	_	_	-1.2	V	I <sub>S</sub> = -0.8A, V <sub>GS</sub> =0V

<sup>\*1</sup> Pw≤10μs, Duty cycle≤1% \*2 Mounted on a ceramic board

#### Electrical characteristic curves

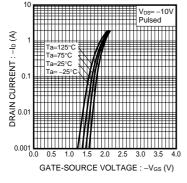


Fig.1 Typical Transfer Characteristics

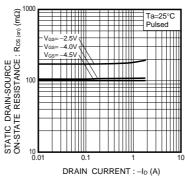


Fig.2 Static Drain-Source On-State Resistance vs. Drain Current

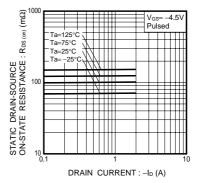


Fig.3 Static Drain-Source On-State Resistance vs. Drain Current

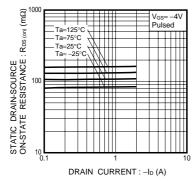


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current

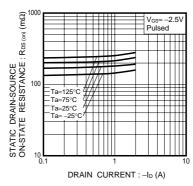


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current

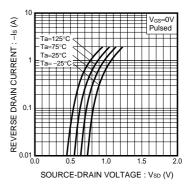


Fig.6 Reverse Drain Current vs. Source-Drain Voltage

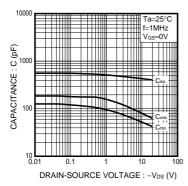


Fig.7 Typical Capacitance vs. Drain-Source Voltage

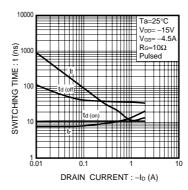


Fig.8 Switching Characteristics

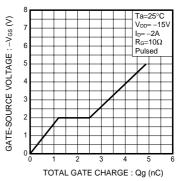


Fig.9 Dynamic Input Characteristics

#### ●Measurement circuits

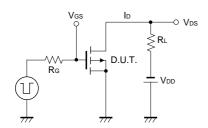


Fig.10 Switching Time Measurement Circuit

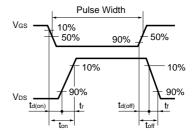


Fig.11 Switching Waveforms

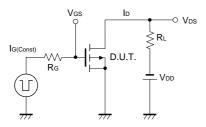


Fig.12 Gate Charge Measurement Circuit

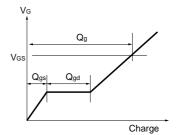


Fig.13 Gate Charge Waveforms

#### **Notes**

- No technical content pages of this document may be reproduced in any form or transmitted by any
  means without prior permission of ROHM CO.,LTD.
- The contents described herein are subject to change without notice. The specifications for the
  product described in this document are for reference only. Upon actual use, therefore, please request
  that specifications to be separately delivered.
- Application circuit diagrams and circuit constants contained herein are shown as examples of standard
  use and operation. Please pay careful attention to the peripheral conditions when designing circuits
  and deciding upon circuit constants in the set.
- Any data, including, but not limited to application circuit diagrams information, described herein are intended only as illustrations of such devices and not as the specifications for such devices. ROHM CO.,LTD. disclaims any warranty that any use of such devices shall be free from infringement of any third party's intellectual property rights or other proprietary rights, and further, assumes no liability of whatsoever nature in the event of any such infringement, or arising from or connected with or related to the use of such devices.
- Upon the sale of any such devices, other than for buyer's right to use such devices itself, resell or
  otherwise dispose of the same, no express or implied right or license to practice or commercially
  exploit any intellectual property rights or other proprietary rights owned or controlled by
- ROHM CO., LTD. is granted to any such buyer.
- Products listed in this document use silicon as a basic material.
   Products listed in this document are no antiradiation design.

The products listed in this document are designed to be used with ordinary electronic equipment or devices (such as audio visual equipment, office-automation equipment, communications devices, electrical appliances and electronic toys).

Should you intend to use these products with equipment or devices which require an extremely high level of reliability and the malfunction of with would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), please be sure to consult with our sales representative in advance.

About Export Control Order in Japan

Products described herein are the objects of controlled goods in Annex 1 (Item 16) of Export Trade Control Order in Japan.

In case of export from Japan, please confirm if it applies to "objective" criteria or an "informed" (by MITI clause) on the basis of "catch all controls for Non-Proliferation of Weapons of Mass Destruction.

